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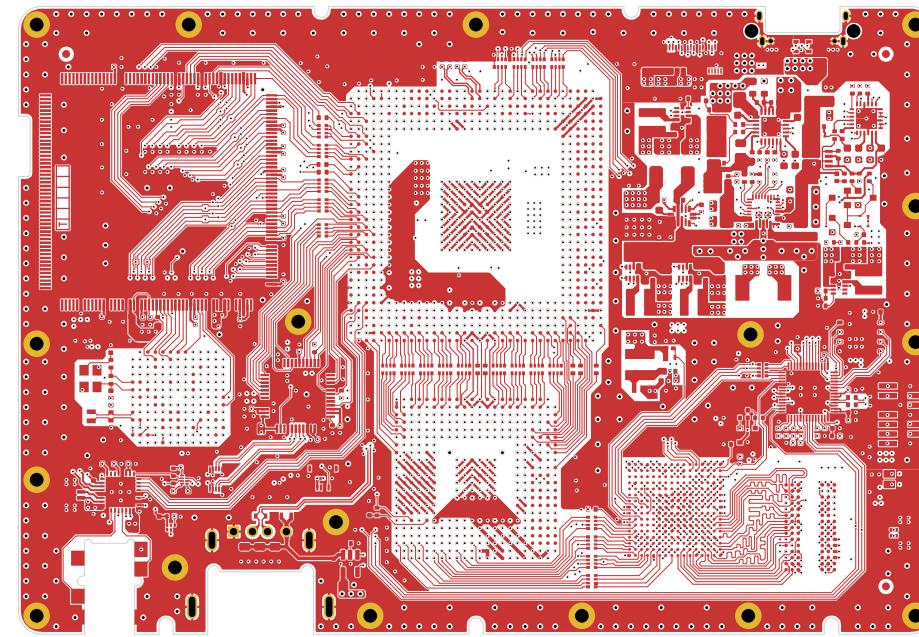
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Rev.	Change History	Originator	Eff. Date	Supplier: JLCPCB.com Stackup: JLC06121H-3313 Material: FR4 TG155 Plating: ENIG 0.0508um Vias: Epoxy filled & capped Sheet: File: PS2_79004_Rev_0_4.kicad_pcb	
0.1	Initial Draft – PS2 circuits only	P. Haid	25. Jan. 2023		
0.2	Add SysCon, Power/Battery Management and Video Processor	P. Haid	02. Oct. 2024		
0.3	Fix soft power switch; optimize BOM & component placement; Redo power routing;	P. Haid	03. Aug. 2025		
D	0.4 Enlarge pads of gamepad connectors for easier soldering; add R616	P. Haid	19. Oct. 2025		
				Title: PS2 AIO Mainboard	
				Size: A4 Date: Rev: 0.4	
				KiCad E.D.A. kicad 7.0.10 Id: 1/1	
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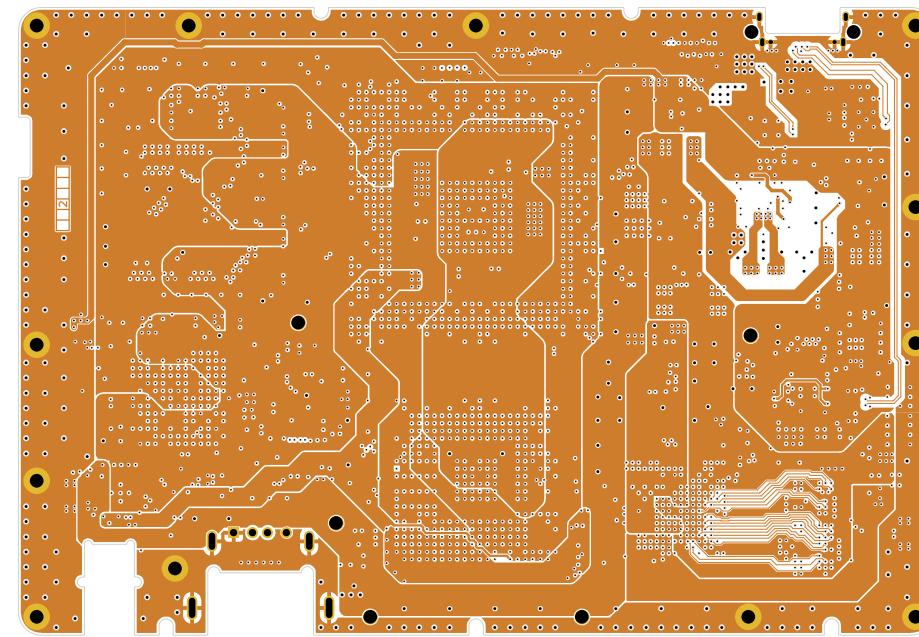
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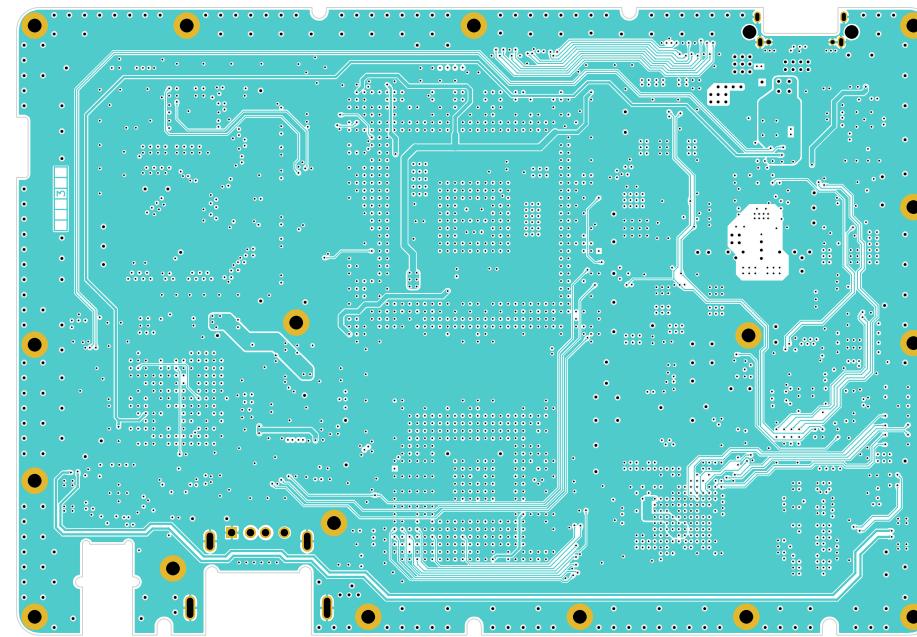
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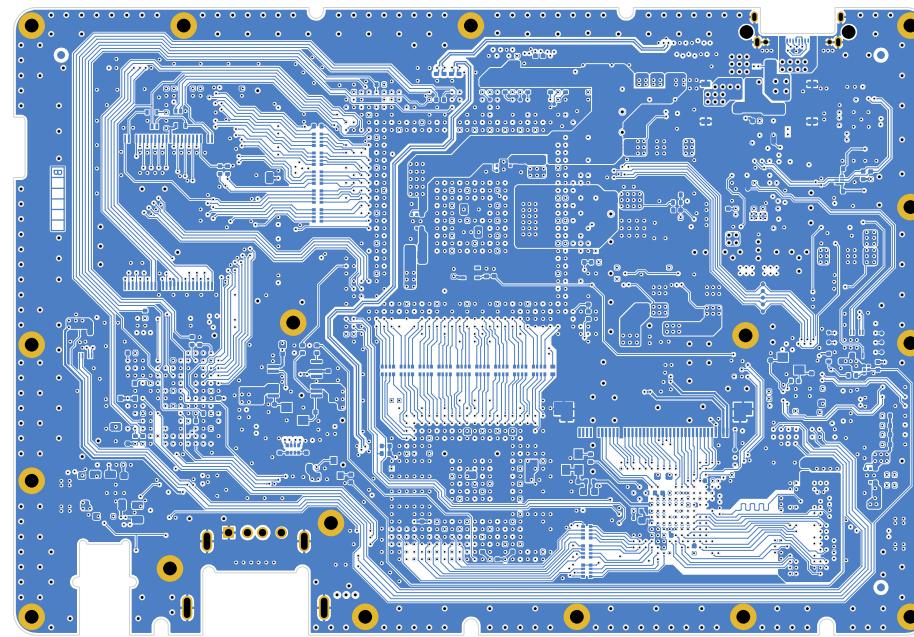
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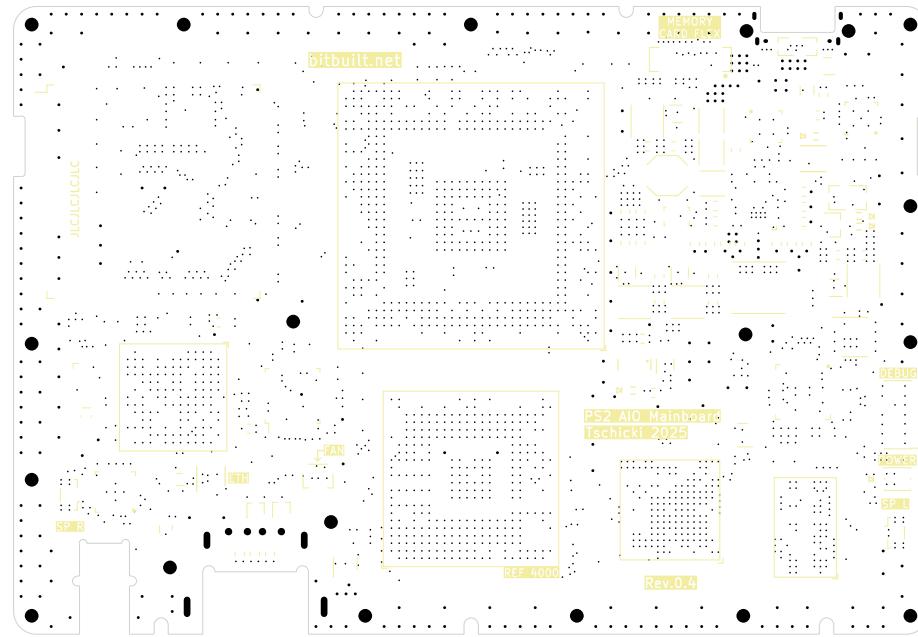


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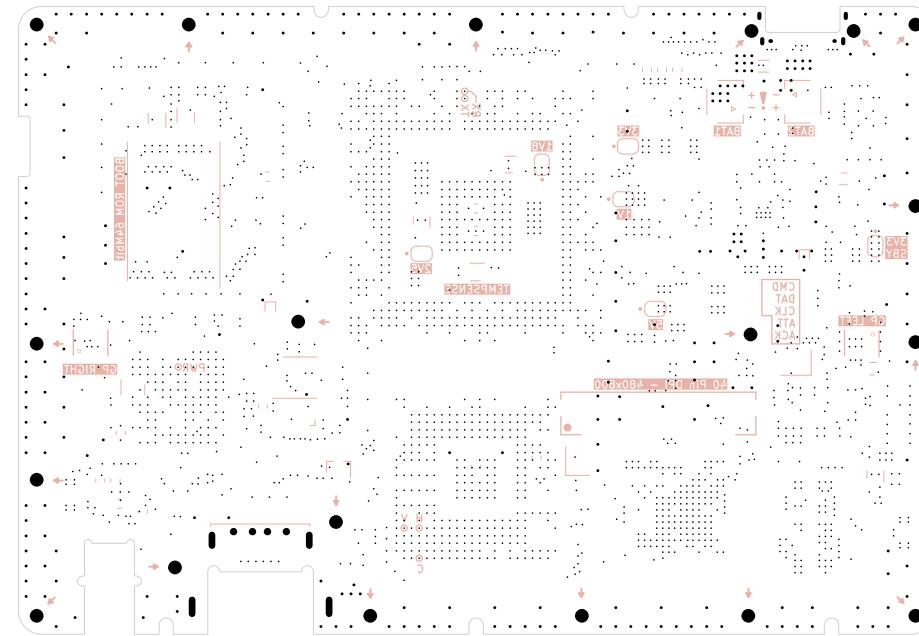
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